



Material Content Data Sheet



Sales Product Name		ESD218-B1-02ELS E6327		Issued		19. July 2018		
MA#		MA001228148						
Package		PG-TSSLP-2-4		Weight*		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.33		3316	
	noble metal	gold	7440-57-5	0.003	1.29		12870	
	inorganic material	silicon	7440-21-3	0.033	15.71	17.33	157062	173248
leadframe	non noble metal	nickel	7440-02-0	0.108	51.43	51.43	514274	514274
wire	noble metal	gold	7440-57-5	0.002	1.18	1.18	11823	11823
encapsulation	organic material	carbon black	1333-86-4	0.000	0.14		1413	
	plastics	epoxy resin	-	0.009	4.10		41022	
	inorganic material	silicondioxide	60676-86-0	0.051	24.05	28.29	240473	282908
leadfinish	noble metal	gold	7440-57-5	0.004	1.75	1.75	17547	17547
plating	noble metal	palladium	7440-05-3	0.000	0.01		76	
	noble metal	gold	7440-57-5	0.000	0.01	0.02	124	200
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com